


Form 1449 (Modified)
**Information Disclosure
Statement By Applicant**

(Use Several Sheets if Necessary)

Atty Docket No.

NSC1P131X1

Applicant:

NGUYEN et al.

Filing Date

2/21/2002

Application No.:

10/080,913

Group

2814
U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
<i>P/2</i>	A	2003/0218258	11-27-2003	CHARLES et al.			
	B						
	C						
	D						
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Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	J							
	K							
	L							
	M							
	N							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
	O	
	P	
	Q	
Examiner		Date Considered <i>3/31/06</i>

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



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U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
D P	A	6,455,920	09/24/02	Fukasawa, et al.	257	620	09/25/98
	B						
	C						
	D						
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	F						
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	I						

Foreign Patent or Published Foreign Patent Application

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	N							

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	Q	
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Atty Docket No. NSC1P131X1/P04314P01 Application No.: 10/080,913
Applicant: Nguyen et al.
Filing Date February 21, 2002 Group 2814

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
P	A	6,228,678	05-2001	Gilleo et al.			
P	B	6,346,296	02-2002	McCarthy et al.			
C							
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Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
J								
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Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication		
P	O	Office Action mailed April 11, 2005 in U.S. Application 10/707,208.		
	P			
	Q			
Examiner		Date Considered		3131P6

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Filing Date

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Group

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U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
DI	A	20030099767	5-2003	Fang			
DF	B	20040002181	1-2004	Scheifers et al.			
DK	C	20050516331	7-2005	Akram			
(D)	D						
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Foreign Patent or Published Foreign Patent Application

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							Yes	
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	K							
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	M							
	N							

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
DK	O	Office Action mailed August 4, 2005 in U.S. Application 10/224,291.
	P	
	Q	
Examiner		Date Considered

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Group

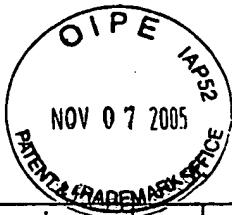
2891

U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
PF	A	5,329,423	07/12/94	Scholz			04/13/93
	B	5,495,439	02/27/96	Morihara			09/07/94
	C	5,500,534	03/19/96	Robinson et al.			03/31/94
	D	5,736,456	04/07/98	Akram			01/17/96
	E	5,767,010	06/16/98	Mis et al.			11/05/96
	F	5,773,359	06/30/98	Mitchell et al.			12/26/95
	G	5,872,633	02/16/99	Holzapfel et al.			02/12/97
	H	5,925,936	07/20/99	Yamaji			02/26/97
	I	5,937,320	08/10/99	Andricacos et al.			04/08/98
	J	5,977,632	11/02/99	Beddingfield			02/02/98
	K	6,171,887	01/09/01	Yamaji			05/04/99
	L	6,307,269	10/23/01	Akiyama et al.			07/10/98
	M	6,316,528	11/13/01	Iida et al.			07/08/99
	N	6,327,158 B1	12/04/01	Kelkar et al.			01/15/99
	O	6,352,881 B1	03/05/02	Nguyen et al.			07/22/99
	P	6,372,547	01/10/02	Nakamura et al.			03/11/98
	Q	6,391,683	05/21/02	Chiu et al.			06/21/00
	R	6,455,920	09/24/02	Fukusawa et al.			09/25/98
	S	6,486,562	11/26/02	Kato			06/07/00
	T	6,507,118	01/14/03	Schueller			07/14/00
PF	U	6,818,550	11/16/04	Shibata			07/11/02
PF	V	6,822,324	11/23/04	Tao et al.			01/28/03

Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
W								
X								
Y								
Z								
A1								



Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
PF	A2	"Polymer Collar WLP™, Wafer Level Package Family", © 2002, downloaded from www.kns.com/prodserv/PDFS/FCD/polymer_collar.pdf , 2 pages.
	A3	"Presenting Polymer Collar WLP™ - A New Wafer Level Package for Improved Solder Joint Reliability", © 2002, downloaded from www.kns.com/prodserv/flipchip/pdf/PC_ad.pdf , 1 page.
	A4	Barrett et al., Kulicke & Soffa, "Polymer Collar WLP™ - A New Wafer Level Package for Improved Solder Joint Reliability", © 2002, downloaded from www.kns.com/resources/articles/PolymerCollar.pdf , 9 pages.
	A5	Bogatin, Eric, "All Dressed Up and Nowhere to Go"; <i>Semiconductor International</i> , May 1, 2002, downloaded December 23, 2003, from www.reed-electronics.com/semiconductor/index.asp?layout=article&articleid=CA213812&rid=0&rme=0&cfid=1 , 2 pages.
DR	A6	Nguyen et al., "Effect of Underfill Fillet Configuration on Flip Chip Package Reliability", SEMI® Technology Symposium: International Electronics Manufacturing Technology (IEMT) Symposium, SEMICON® West 2002.
Examiner <i>[Signature]</i>		Date Considered <i>3/3/05</i>

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Form 1449 (Modified) Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)		Atty Docket No. NSC1P131X1	Application No.: 10/080,913
		Applicant: Nguyen et al.	Group 2823
		Filing Date 02/21/02	

U.S. Patent Documents

Examiner Initial	No.	Patent No. or Pub. No.	Date	Patentee	Class	Sub-class	Filing Date
P	A	6,190,940	02/20/01	Defelice et al.			
P	B	6,258,626	07/10/01	Wang et al.			
P	C	2002/0109228	08/15/02	Buchwalter et al.			
P	D	2002/0171152	11/21/02	Miyazaki			
P	E	2003/0001283	01/02/03	Kumamoto			
P	F	2003/0087475	05/08/03	Sterrett et al.			
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Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
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